

Features

- 650-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching

${\bf \mathring{B}enefits}^{\rm Positive\ \check{T}emperature\ \check{Coefficient\ on\ V_F}$

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor Drives

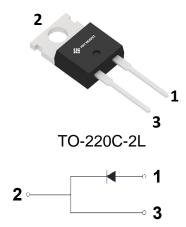




Part Number	Package	Qty(PCS)
HFFSP2065A	TO-220C-2L	50

Maximum Ratings (T_C = 25 °C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions
V_{RRM}	Repetitive Peak Reverse Voltage	650	V	
V _{RSM}	Surge Peak Reverse Voltage	650	V	
V _{DC}	DC Blocking Voltage	650	V	
I _F	Continuous Forward Current	20	А	T _c =125°C
I _{FRM}	Repetitive Peak Forward Surge Current	81	А	T _c =110°C, t _p =10 ms, Half Sine Wave
I _{FSM}	Non-Repetitive Peak Forward Surge Current	123 104	А	T_c =25°C, t_p = 10 ms, Half Sine Wave T_c =150°C, t_p = 10 ms, Half Sine Wave
I _{F,Max}	Non-Repetitive Peak Forward Surge Current	450	А	T_c =25°C, t_p = 10 µs, Pulse
P _{tot}	Power Dissipation	115	W	T _c =25°C
T_{J} , T_{stg}	Operating Junction and Storage Temperature	-55 to +175	°C	





Electrical Characteristics

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions
V _F	Forward Voltage	1.35 1.5	1.5 -	V	I _F = 20 A ,T _J =25°C I _F = 20 A ,T _J =175°C
I _R	Reverse Current	0.06 12	100 -	μΑ	V _R = 650 V T _J =25°C V _R = 650 V T _J =175°C
Q _c	Total Capacitive Charge	24		nC	$V_R = 400 \text{ V, } I_F = 10 \text{ A}$ $di/dt = 500 \text{ A}/\mu\text{s}$ $T_J = 25^{\circ}\text{C}$
С	Total Capacitance	1000 91		pF	V _R = 0 V, T _J = 25°C, f = 1 MHz V _R = 400 V, T _J = 25°C, f = 1 MHz
E _{ava}	Non-repetetive Avaranche Energy	220		mJ	L=1mH

Note: This is a majority carrier diode, so there is no reverse recovery charge.

Thermal Characteristics

Symbol	Parameter	Тур.	Unit
$R_{JC^{\theta}}$	Thermal Resistance from Junction to Case	0.87	°C/W

Typical Performance

Fig.1 V_F - I_F Characteristics

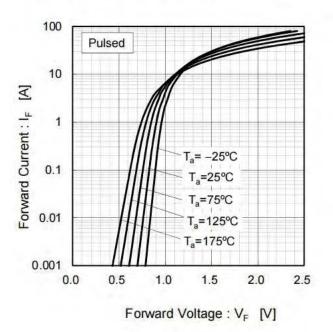
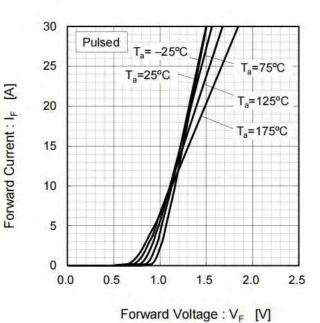
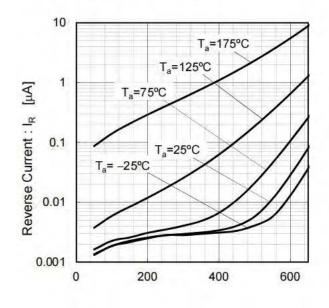


Fig. 2 V_F - I_F Characteristics



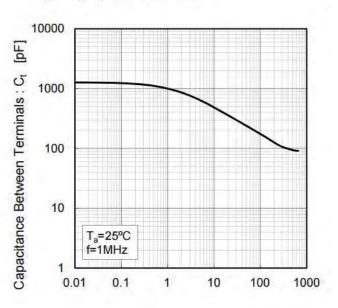
Typical Performance

Fig. 3 V_R - I_R Characteristics



Reverse Voltage : V_R [V]

Fig.4 V_R-C_t Characteristics



Reverse Voltage : V_R [V]

Fig.5 Typical Transient Thermal Resistance vs. Pulse Width

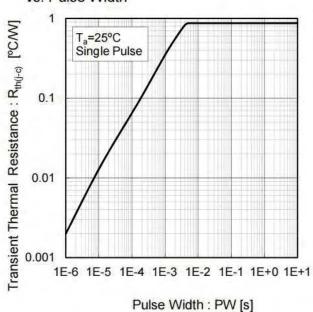
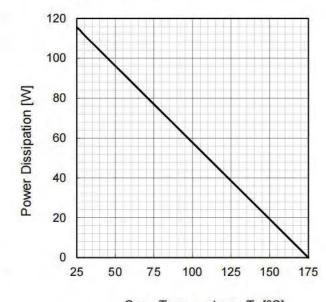


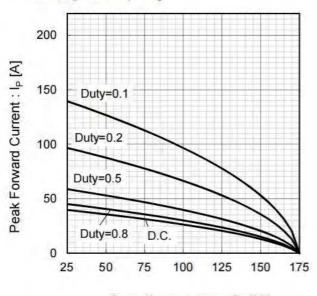
Fig.6 Power Dissipation



Case Temperature : T_c [°C]

Typical Performance

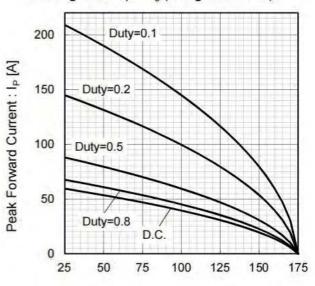
Fig.7*3 Maximum peak forward current derating curve $I_P - T_c$



Case Temperature : T_c [°C]

*3 Based on max Vf, max R_{th(j-c)} Valid for switching of above 10kHz, excluding D.C. curve.

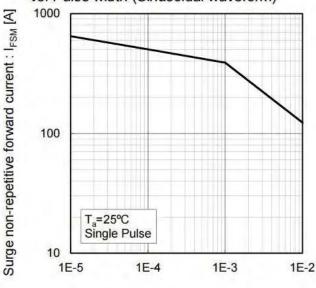
Fig.8*4 Typical peak forward current derating curve I_P - T_c (Not guaranteed)



Case Temperature : T_c [°C]

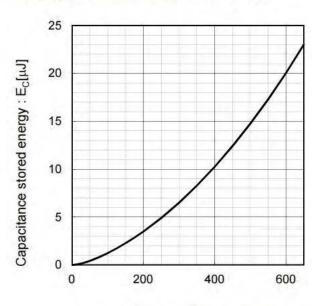
*4 Based on typ Vf, typ R_{th(j-c)} Typical value, not guaranteed Valid for switching of above 10kHz, excluding D.C. curve

Fig.9 Surge non-repetitive forward current vs. Pulse width (Sinusoidal waveform)



Pulse Width: PW [s]

Fig. 10 Typical capacitance store energy

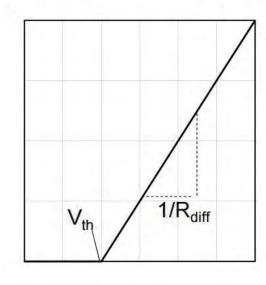


Reverse Voltage : V_R [V]

Typical Performance

Forward Current : I_F

Fig.11 Equivalent forward current curve



Forward Voltage: V_F

$$V_F = V_{th} + R_{diff} I_F$$

$$V_{th} (T_j) = a_0 + a_1 T_j$$

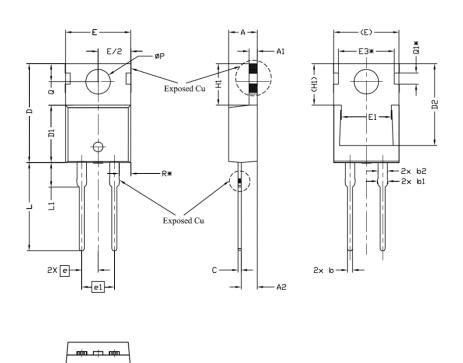
$$R_{diff} (T_j) = b_0 + b_1 T_j + b_2 T_j^2$$

Symbol	Typical Value	Unit
a ₀	9.66E-01	V
a ₁	- 1.10E-03	V/°C
b ₀	1.76E-02	Ω
b ₁	3.73E-05	Ω/°C
b ₂	3.84E-07	$\Omega/^{\circ}C^{2}$

 T_j in °C; -55 °C < T_j < 175°C ; I_F < 40A

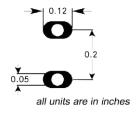


Package Information TO-220C-2L

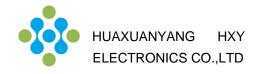


	[DIMENSIONS			
SYMBOL	YMBOL MIN. NOM, MAX.		MAX.	NOTES	
А	4.24 4.44 4.64		4,64		
A1	1.15	1.27	1.40		
A2	2.30	2.48	2.70		
b	0.70	0.80	0.90		
b1	1.20	1.55	1.75		
b2	1.20	1.45	1.70		
С	0.40	0.50	0.60		
D	14.70	15.37	16.00	4	
D1	8.82	8.92	9.02		
D2	12.43	12.73	12.83	5	
E	9.96 10.16		10.36	4,5	
E1	6,86	7.77	8,89	5	
E3*	8.70REF.				
е		2.54BSC			
e1		5.08BSC			
H1	6.30	6.45	6.60	5,6	
L	13.47	13.72	13.97		
L1	3.60	3.80	4.00		
ØP	3.75	3.84	3,93		
Q	2,60	2,80	3,00		
Q1*	1.73REF				
R*	1.82REF.				

Recommended Solder Pad Layout



T0220-2L



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